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PPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
10/787,086	02/27/2004	Takeshi Kato	NIT-156-05	4293
7590 06/29/2005			EXAMINER	
MATTINGLY, STANGER & MALUR, P.C.			SONG, SARAH U	
Suite 370 1800 Diagonal Road		ART UNIT	PAPER NUMBER	
Alexandria, VA 22314			2874	
			DATE MAILED: 06/29/2005	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
	10/787,086	KATO ET AL.				
Office Action Summary	Examiner	Art Unit				
	Sarah Song	2874				
The MAILING DATE of this communication app	ears on the cover sheet with the c	orrespondence address				
Period for Reply						
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply - If NO period for reply is specified above, the maximum statutory period - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	si6(a). In no event, however, may a reply be time within the statutory minimum of thirty (30) days fill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on 28 Ma	arch 2005 and 28 April 2005.					
	action is non-final.					
3) Since this application is in condition for allowan		secution as to the merits is				
closed in accordance with the practice under E	· · · · · · · · · · · · · · · · · · ·					
Disposition of Claims						
4)⊠ Claim(s) <u>20-33</u> is/are pending in the application	1					
	4a) Of the above claim(s) is/are withdrawn from consideration.					
5) Claim(s) is/are allowed.						
6)⊠ Claim(s) <u>20-33</u> is/are rejected.		•				
7) Claim(s) is/are objected to.						
8) Claim(s) are subject to restriction and/or	election requirement.	•				
Application Papers						
9) The specification is objected to by the Examiner	г.					
10)⊠ The drawing(s) filed on 27 February 2004 is/are		d to by the Examiner.				
Applicant may not request that any objection to the						
Replacement drawing sheet(s) including the correcti	on is required if the drawing(s) is obj	ected to. See 37 CFR 1.121(d).				
11)☐ The oath or declaration is objected to by the Ex	aminer. Note the attached Office	Action or form PTO-152.				
Priority under 35 U.S.C. § 119						
12)⊠ Acknowledgment is made of a claim for foreign	priority under 35 U.S.C. § 119(a)	-(d) or (f).				
a)⊠ All b)□ Some * c)□ None of:	, ,					
1. Certified copies of the priority documents	s have been received.					
2. Certified copies of the priority documents	s have been received in Application	on No. <u>09/402,585</u> .				
Copies of the certified copies of the prior	ity documents have been receive	ed in this National Stage				
application from the International Bureau	` ''					
* See the attached detailed Office action for a list of	of the certified copies not receive	d:				
Attachment(s)	,, 					
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)	4) ∐ Interview Summary Paper No(s)/Mail Da					
3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date		atent Application (PTO-152)				

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DETAILED ACTION

Continued Examination Under 37 CFR 1.114

- 1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on March 28, 2005 has been entered. Claims 20, 25, 30 and 31 have been amended. Claims 32 and 33 are newly added. Claims 20-33 are pending.
- 2. Claims 20-24, 30 and 32 are rejected under 35 U.S.C. 103(a) as being unpatentable over Blonder et al. (U.S. Patent 4,897,711 newly cited) in view of Collins et al. (U.S. Patent 5,852,696 previously relied upon).
- 3. Regarding claim 20, Blonder et al. discloses an optical module comprising:
 - an optical device 11;
 - an optical fiber 20 optically coupled to said optical device at one end; and
 - a lead frame 12 electrically coupled to said optical device;
 - wherein said optical device and said optical fiber are mounted on a non-metal substrate 22;
 - and silicone is filled between a face of said optical device that is optically coupled to said optical fiber, and an end of said optical fiber that is optically coupled to said optical device (column 7, lines 1-3).

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4. Blonder et al. discloses the claimed invention except for a communication processing unit.

- 5. Collins et al. discloses that it is known for optoelectronic devices to be coupled to a communication processing unit, such as a fiber to the home telecommunications network (column 1, lines 60-64).
- 6. Blonder et al. and Collins et al. are analogous art because they are from the same field of endeavor, that is packaged optical and optoelectronic devices.
- 7. At the time of the invention, it would have been obvious to a person of ordinary skill in the art to couple a communication processing unit with the device of Blonder et al.
- 8. The motivation for doing so would have been to provide a transmission network for efficient low-cost, high-speed communications.
- 9. Blonder et al. also does not expressly disclose the silicone to be a resin.
- 10. Hirai et al. discloses an optical junction comprising a silicone resin filled between abutting end faces of optical waveguide unit 60, and optical fiber units 70 and 80 (column 14, lines 4-9). It is additionally noted that silicone resin is a transparent resin.
- 11. Blonder et al. and Hirai et al. are analogous art as pertaining to optical devices.
- 12. One of ordinary skill in the art at the time the invention was made would have recognized the silicone disclosed by Blonder et al. to be a silicone resin.
- 13. Regarding claim 21, the refractive index of the transparent silicone resin is an index matching resin (see column 14, lines 4-9 of Hirai et al.). Therefore, the refractive index of the resin matches that of the optical fiber.

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14. Regarding claim 22, Hirai et al. does not expressly disclose that the silicone resin is a gel or is in gel form. However, silicone is well known in the art to be readily available in gel form. Therefore it would have been obvious to one having ordinary skill in the art at the time the invention was made to provide transparent resin in gel form in order to facilitate application of the resin at the interface.

- 15. Regarding claim 23, the optical device, said end of the optical fiber, and said substrate are placed inside a resin casing (column 5, liness 65+ of Blonder et al.).
- 16. Regarding claim 24, it is evident that the optical device, said end of the optical fiber and said substrate are placed in a cavity inside said resin casing, the cavity being filled by the optical device, said end of the optical fiber, and said substrate.
- 17. Regarding claim 30, Blonder et al. discloses that the resin case is molded ("molding operations associated with encapsulating the subassembly in a package") but does not expressly disclose that the resin casing is formed by transfer molding. However, the method of forming a device is not germane to the issue of patentability of the device itself. Therefore, this limitation has not been given patentable weight.
- 18. Regarding claim 32, the substrate is a silicon substrate (column 3, line 36).
- 19. Claims 25-29, 31 and 33 are rejected under 35 U.S.C. 103(a) as being unpatentable over Blonder et al. in view of Hirai et al.
- 20. Regarding claim 25, Regarding claim 20, Blonder et al. discloses an optical module comprising:
 - an optical device 11;
 - an optical fiber 20 optically coupled to said optical device at one end; and

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- a lead frame 12 electrically coupled to said optical device;

- wherein said optical device and said optical fiber are mounted on a non-metal substrate 22;
- . and silicone is filled between a face of said optical device that is optically coupled to said optical fiber, and an end of said optical fiber that is optically coupled to said optical device (column 7, lines 1-3).
- 21. Blonder et al. does not expressly disclose the silicone to be a resin.
- 22. Hirai et al. discloses an optical junction comprising a silicone resin filled between abutting end faces of optical waveguide unit 60, and optical fiber units 70 and 80 (column 14, lines 4-9). It is additionally noted that silicone resin is a transparent resin.
- 23. Blonder et al. and Hirai et al. are analogous art as pertaining to optical devices.
- 24. One of ordinary skill in the art at the time the invention was made would have recognized the silicone disclosed by Blonder et al. to be a silicone resin.
- 25. Regarding claim 26, as noted above the refractive index of the transparent silicone resin is an index matching resin (see column 14, lines 4-9 of Hirai et al.). Therefore, the refractive index of the resin matches that of the optical fiber.
- 26. Regarding claim 27, Hirai et al. does not expressly disclose that the silicone resin is a gel or is in gel form. However, silicone is well known in the art to be readily available in gel form. Therefore it would have been obvious to one having ordinary skill in the art at the time the invention was made to provide transparent resin in gel form in order to facilitate application of the resin at the interface.

27. Regarding claim 28, the optical device, said end of the optical fiber, and said substrate are placed inside a resin casing (column 5, lines 65+ of Blonder et al.).

- 28. Regarding claim 29, it is evident that the optical device, said end of the optical fiber and said substrate are placed in a cavity inside said resin casing, the cavity being filled by the optical device, said end of the optical fiber, and said substrate.
- 29. Regarding claim 31, Blonder et al. discloses that the resin case is molded ("molding operations associated with encapsulating the subassembly in a package") but does not expressly disclose that the resin casing is formed by transfer molding. However, the method of forming a device is not germane to the issue of patentability of the device itself. Therefore, this limitation has not been given patentable weight.
- 30. Regarding claim 33, the substrate is a silicon substrate (column 3, line 36).

Response to Arguments

31. Applicant's arguments with respect to claims 20-33 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Sarah Song whose telephone number is 571-272-2359. The examiner can normally be reached on M-Th 7:30am - 6:00pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Rodney Bovernick can be reached on 571-272-2344. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Patent Examiner

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